Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1-10. (Cancelled)

11. (Previously Presented) A semiconductor laser device comprising:

a semiconductor laser element;

a frame having a front face on which the semiconductor laser element is placed; and

a resin molded portion that covers the front and back faces of the frame,

wherein, on a front face side of the frame,

the semiconductor laser element is enclosed with the resin molded portion, and

the resin molded portion has an open front serving as a laser beam emission window,

wherein, on a back face side of the frame, there is provided an exposed portion enclosed with the resin molded portion having an open front, the exposed portion where the frame is exposed to an outside, and

wherein the frame includes

an element placement portion on which the semiconductor laser element is placed,

a lead portion that is integrally formed with the element placement portion, the lead portion that serves as a current path with a wire connected thereto, and

a tapered portion provided between the element placement portion and the lead portion, the tapered portion whose width is gradually reduced from the element placement portion toward the lead portion.

12. (Previously Presented) The semiconductor laser device of claim 1, further comprising:

a gate mark of an injection gate through which molding resin is injected, the gate mark provided above the tapered portion.

13. (Previously Presented) A semiconductor laser device comprising:

a semiconductor laser element;

a frame having a front face on which the semiconductor laser element is placed; and

a resin molded portion that covers the front and back faces of the frame,

wherein, on a front face side of the frame,

the semiconductor laser element is enclosed with the resin molded portion, and

the resin molded portion has an open front serving as a laser beam emission window,

wherein, on a back face side of the frame, there is provided an exposed portion enclosed with the resin molded portion having an open front, the exposed portion where the frame is exposed to an outside, and

wherein the frame includes

an element placement portion on which the semiconductor laser element is placed, and

a lead portion having a width of 0.4 mm or more that is integrally formed with the element placement portion, the lead portion that serves as a current path with a wire connected thereto.

14. (Previously Presented) A semiconductor laser device comprising:

a semiconductor laser element;

a frame having a front face on which the semiconductor laser element is placed; and

a resin molded portion that covers the front and back faces of the frame,

wherein, on a front face side of the frame,

the semiconductor laser element is enclosed with the resin molded portion, and

the resin molded portion has an open front serving as a laser beam emission window,

wherein, on a back face side of the frame, there is provided an exposed portion enclosed with the resin molded portion having an open front, the exposed portion where the frame is exposed to an outside,

wherein the frame includes

an element placement portion on which the semiconductor laser element is placed,

a lead portion that is formed integrally with the element placement portion, the lead portion that serves as a current path with a wire connected thereto, and

subframes that are arranged in parallel on both sides of the lead portion and are integrated with the lead portion by the resin molded portion, the subframes that serve as current paths with wires connected thereto, and

wherein a width of the lead portion is made greater than a width of each of the subframes.

15. (Cancelled)

16. (Cancelled)